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(12) **United States Design Patent**
Podubni

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- (54) **MODULAR CIRCUIT BOARD**
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- (73) Assignee: **TinyPCB, Inc.**
- (**) Term: **15 Years**
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- (51) **LOC (11) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/182**
- (58) **Field of Classification Search**
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361/761, 807; 439/55, 65, 68, 76.1, 92,
439/93, 95
CPC H05K 3/00; H05K 3/30; H05K 3/301;
H05K 3/303; H05K 3/34; H05K 3/3405;
H05K 3/341; H05K 3/36; H05K 3/361;
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H05K 7/1422; H05K 7/00; H05K 1/18;
H05K 1/02; H05K 1/181; H05K 1/182;
H05K 1/183; H05K 1/184; H05K 1/189;
H05K 1/00
See application file for complete search history.

- (56) **References Cited**
U.S. PATENT DOCUMENTS
2,896,033 A * 7/1959 Hartz H01H 19/585
200/11 D
3,072,734 A * 1/1963 Fox H02B 1/043
174/254
D279,670 S * 7/1985 Lukits D13/182
4,602,271 A * 7/1986 Dougherty, Jr. H01L 23/5385
257/697

- 4,715,928 A * 12/1987 Hamby H05K 3/4691
156/150
D319,045 S * 8/1991 Hasegawa D13/182
D319,629 S * 9/1991 Hasegawa D13/182
D319,814 S * 9/1991 Hasegawa D13/182
D397,093 S * 8/1998 Kim, II D13/182
5,895,967 A * 4/1999 Stearns H01L 23/3128
257/691
D429,704 S * 8/2000 Kang D13/182
6,121,554 A * 9/2000 Kamikawa H05K 1/113
174/255
D440,209 S * 4/2001 Kang D13/182
D442,149 S * 5/2001 Kang D13/182
D442,150 S * 5/2001 Kang D13/182
D442,567 S * 5/2001 Kang D13/182
D457,146 S * 5/2002 Yamamoto D13/182
6,418,030 B1 * 7/2002 Yamaguchi H01L 23/24
257/698
6,462,570 B1 10/2002 Price et al.
D466,093 S * 11/2002 Ebihara D13/182
D471,167 S * 3/2003 Ebihara D13/182

(Continued)

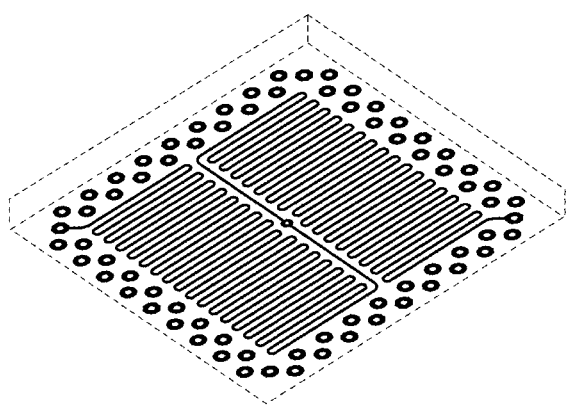
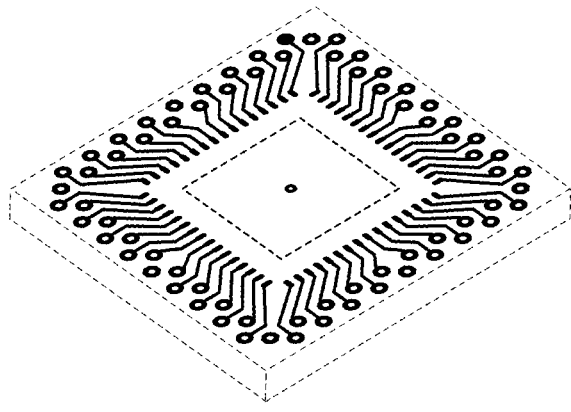
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(57) **CLAIM**
The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;
FIG. 2 is a bottom perspective view thereof;
FIG. 3 is a top view thereof;
FIG. 4 is a bottom view thereof; and,
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D474,773	S *	5/2003	Kondo	D13/182
D485,536	S *	1/2004	Dang	D13/182
6,936,916	B2 *	8/2005	Moxham	H01L 23/13 174/256
D552,048	S *	10/2007	He	D13/182
D556,158	S *	11/2007	Kong	D13/182
7,511,228	B2	3/2009	Yaung et al.		
D599,308	S *	9/2009	Blumberg, Jr.	D13/182
D605,613	S *	12/2009	Carter	D13/182
D639,756	S *	6/2011	Greene, Jr.	D13/182
D642,546	S *	8/2011	Greene, Jr.	D13/182
D645,039	S *	9/2011	Chen	D14/341
8,113,888	B2 *	2/2012	Carter	H01R 9/03 439/676
D676,004	S *	2/2013	Lyubachev	D13/182
D699,201	S *	2/2014	Petsch	D13/182
D768,115	S *	10/2016	Kazanchian	D13/182
D794,586	S *	8/2017	Takahashi	D13/182
D799,438	S *	10/2017	Takahashi	D13/182
D804,437	S *	12/2017	Kantor	D13/182
2009/0250246	A1	10/2009	Yaung et al.		

* cited by examiner

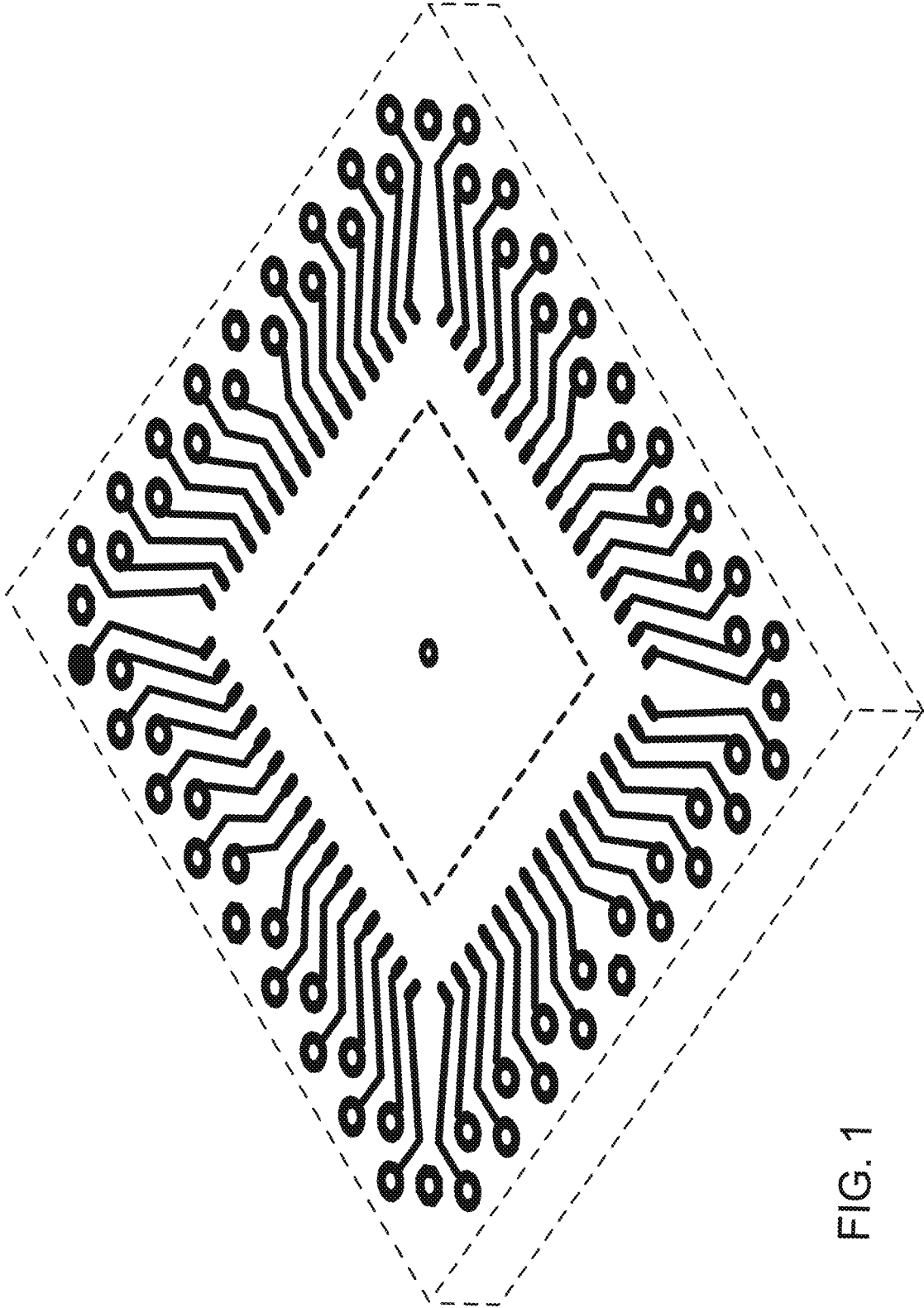


FIG. 1

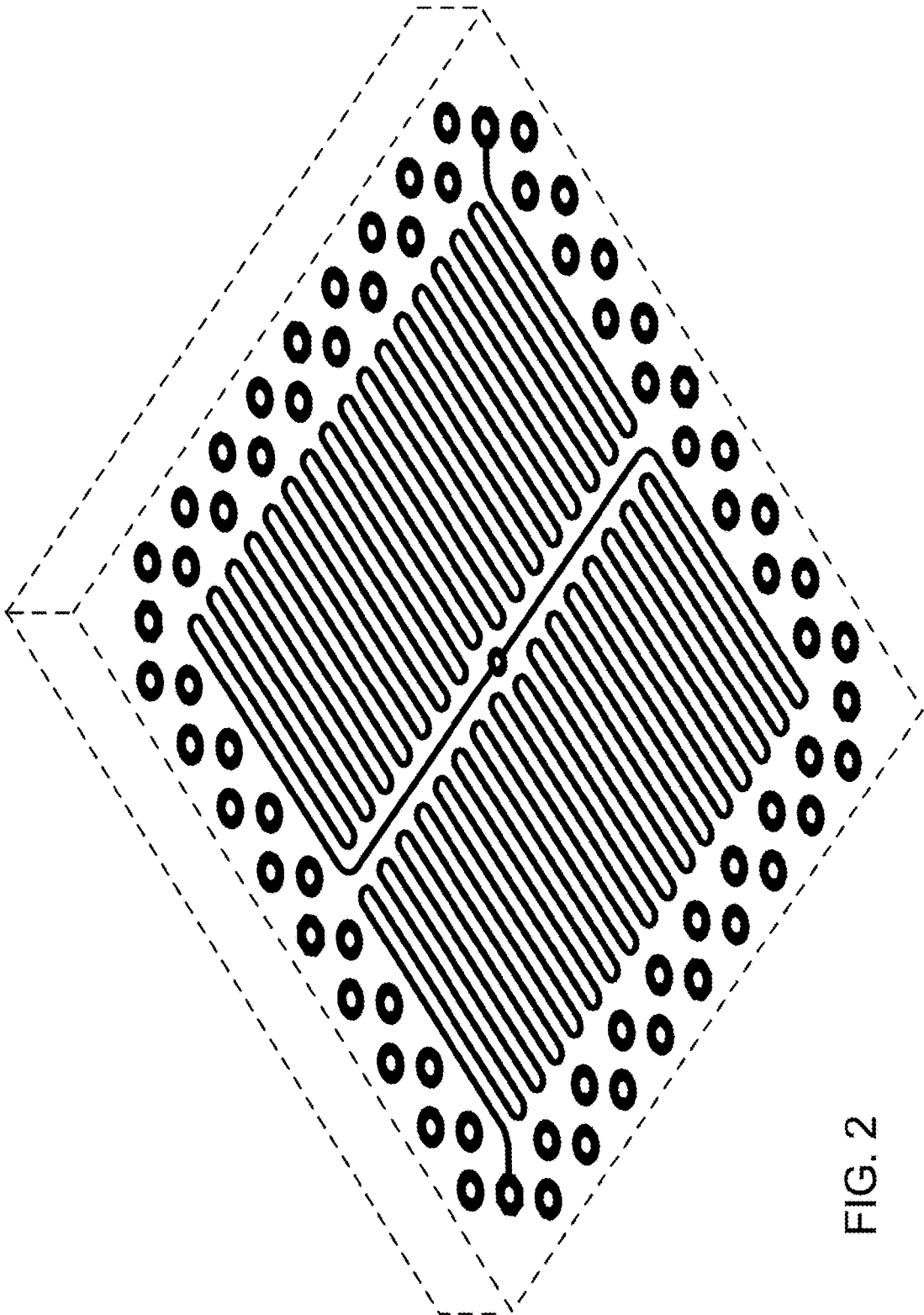


FIG. 2

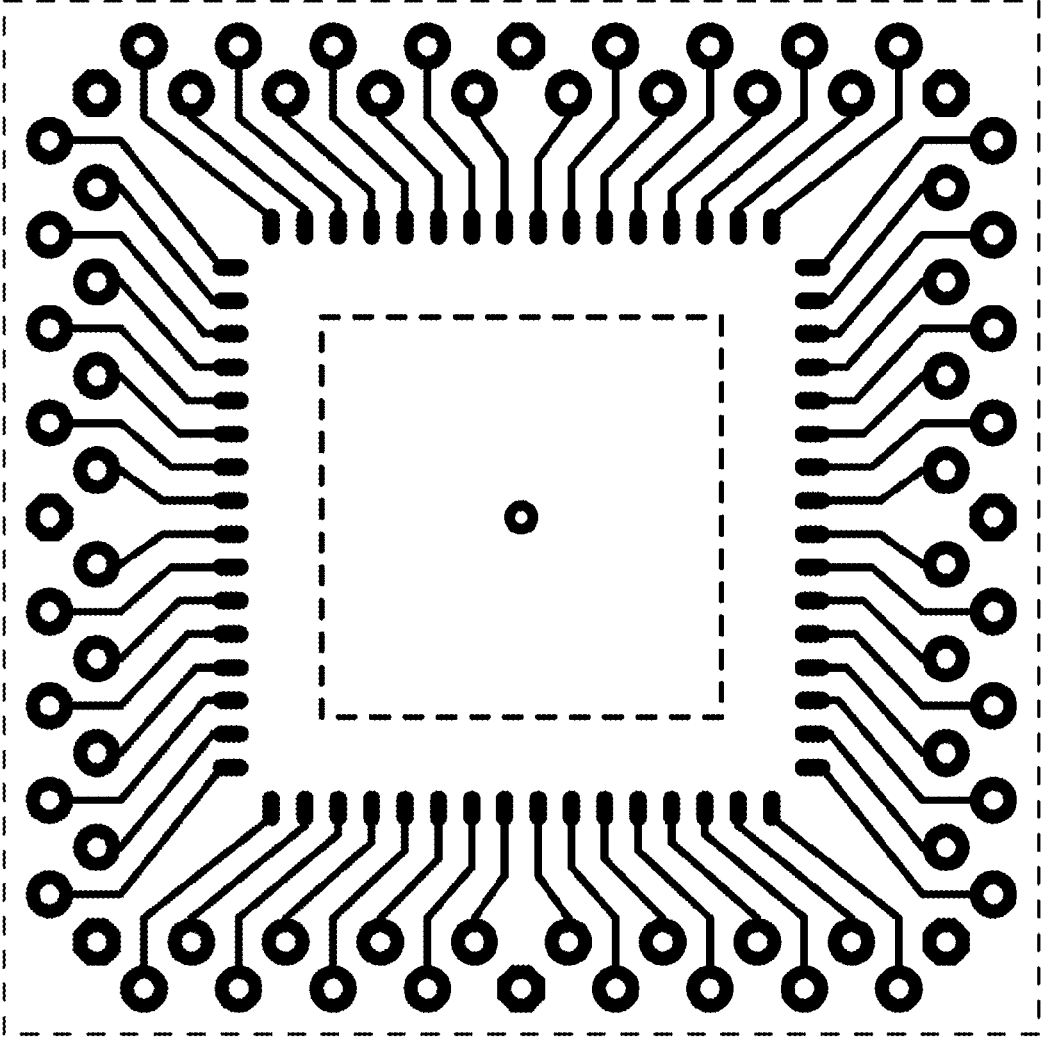


FIG. 3

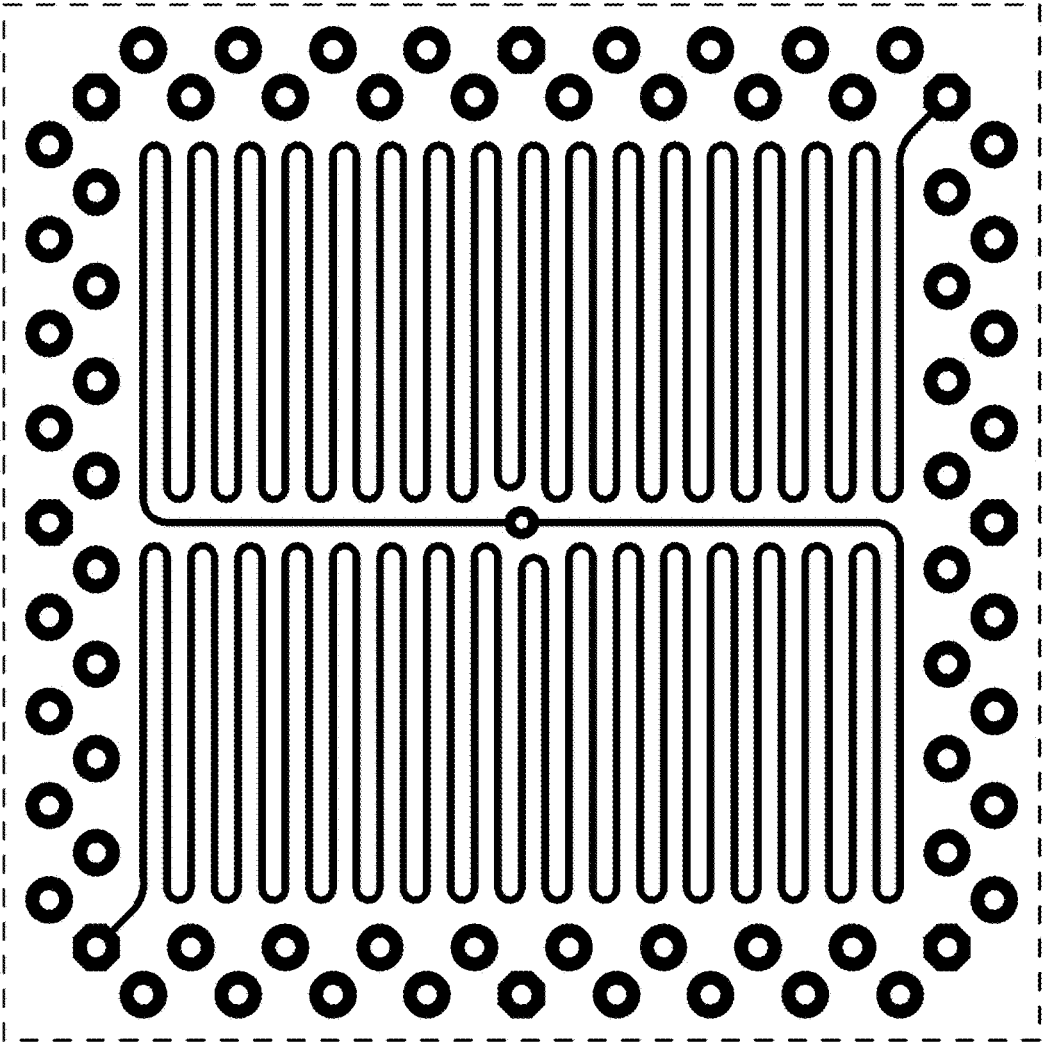


FIG. 4



FIG. 5